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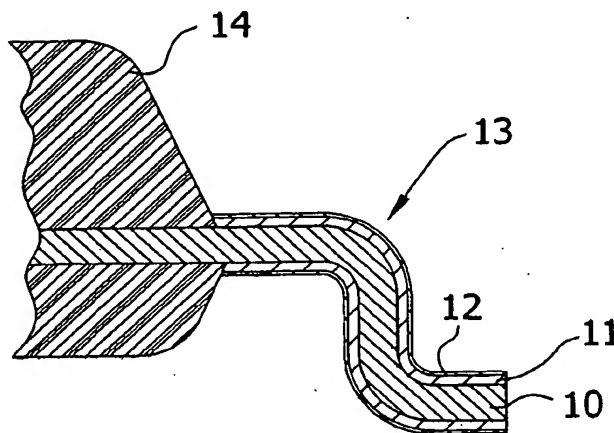
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(54) Title: **PRESERVING SOLDERABILITY AND INHIBITING WHISKER GROWTH IN TIN SURFACES OF ELECTRONIC COMPONENTS**



(57) Abstract: A method for reducing whisker formation and preserving solderability in tin coatings over metal features of electronic components. The tin coating has internal tensile stress and is between about 0.5 m and about 4.0 m in thickness. There is a nickel-based layer under the tin coating.

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